

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.01	2.3	0.02
	Doped Silicon	Silicon (Si)	7440-21-3	0.42	97.7	0.78
Subtotal				0.43	100	0.8
Clip Frame	Copper alloy	Phosphorous (P)	7723-14-0	0	0.04	0
	Copper alloy	Iron (Fe)	7439-89-6	0	0.1	0.01
	Copper alloy	Copper (Cu)	7440-50-8	3.35	99.86	6.19
Subtotal				3.35	100	6.2
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.06	5.0	0.11
	Lead alloy	Silver (Ag)	7440-22-4	0.03	2.5	0.05
	Lead alloy	Lead (Pb)	7439-92-1	1.07	92.5	1.99
Subtotal				1.16	100	2.15
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.13	100.0	2.1
Subtotal				1.13	100	2.1
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.54	8.0	8.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.99	8.8	9.24
	Filler	Silica fused	60676-86-0	47.07	83.0	87.15
	Carbon Black	Carbon black	1333-86-4	0.11	0.2	0.21
Subtotal				56.71	100	105
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.04	0.03
	Copper alloy	Iron (Fe)	7439-89-6	0.04	0.1	0.07
	Copper alloy	Copper (Cu)	7440-50-8	37.16	99.86	68.8
Subtotal				37.21	100	68.9
Total				99.99	100	185.15

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